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- [54] **METHOD FOR FABRICATING SELF-ASSEMBLING MICROSTRUCTURES**
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- [52] U.S. Cl. **257/618; 257/622; 257/623; 257/627; 257/628**
- [58] Field of Search **257/618, 622, 257/623, 627, 628**

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[57] ABSTRACT

A method for assembling microstructures onto a substrate through fluid transport. The microstructures being shaped blocks self-align into recessed regions located on a substrate such that the microstructure becomes integral with the substrate **20, 70, 90, 120, 200**. The improved method includes a step of transferring the shaped blocks into a fluid to create a slurry. Such slurry is then poured evenly over the top surface of a substrate having recessed regions thereon. The microstructure via the shape and fluid tumbles onto the surface of the substrate, self-aligns, and engages into a recessed region.

34 Claims, 9 Drawing Sheets

